

**Glued SAM data sheet SAM- $\lambda$ -A- $\tau$ -4.0-12.7g-c or SAM- $\lambda$ -A- $\tau$ -4.0-12.7g-e**

GaAs chip area                      standard:       4.0 mm x 4.0 mm  
  optional:       other dimensions on request

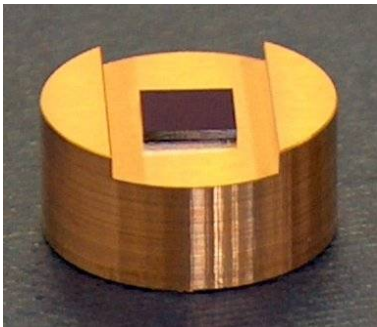
Chip thickness                    standard:       450  $\mu$ m

Front side protection            the SAM is protected with a dielectric front layer.

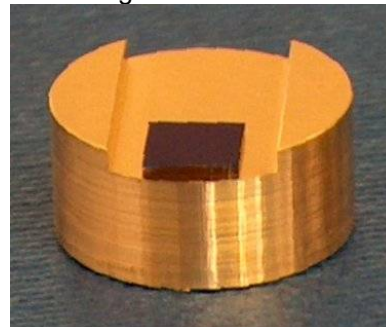
The SAM chip is glued on a gold plated Cu-cylinder with 12.7 mm  $\varnothing$  using a thermal conducting glue. The glue provides a low thermal resistance between the SAM and the mount.

- The **standard** position of the SAM is at the center of the mount → x = [4.0-12.7g-c](#).
- **Optional** the SAM can be soldered on the edge of the mount without extra charges → x = [4.0-12.7g-e](#).

Center mounted SAM



Edge mounted SAM



***Mount***

Cu-cylinder,  $\varnothing$  = 12.7 mm  
                  l = 6.0 mm